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(12) **United States Design Patent**  
**Sato**

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(54) **HEAT RADIATION FIN OF HEAT INSULATING CYLINDER FOR MANUFACTURING SEMICONDUCTOR WAFERS**

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(73) Assignee: **Tokyo Electron Limited**, Minato-Ku (JP)

(\*\*) Term: **14 Years**

(21) Appl. No.: **29/342,852**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** ..... **13-03**

(52) **U.S. Cl.** ..... **D13/182**

(58) **Field of Classification Search** ..... D13/182;  
206/454, 711; 118/728, 729; 211/41.18;  
432/241, 253, 258

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for a heat radiation fin of heat insulating cylinder for manufacturing semiconductor wafers, as shown and described.

**DESCRIPTION**

FIG. 1 is front perspective view of a heat radiation fin of heat insulating cylinder for manufacturing semiconductor wafers illustrating my new design;

FIG. 2 is a front view thereof;

FIG. 3 is a rear view thereof;

FIG. 4 is a right side view thereof;

FIG. 5 is a left side view thereof;

FIG. 6 is a top plan view thereof;

FIG. 7 is a bottom plan view thereof;

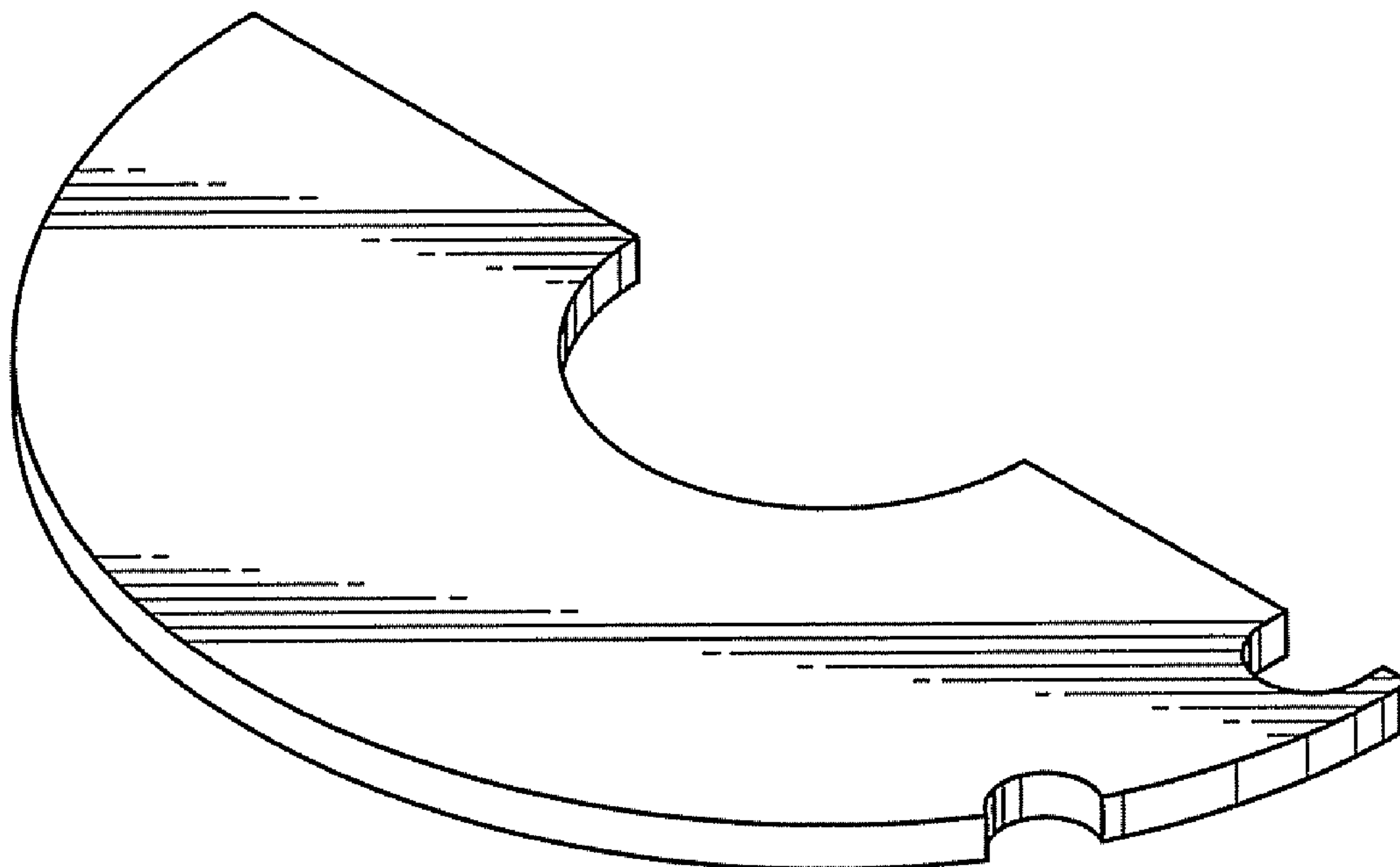
FIG. 8 is a cross-sectional view thereof taken through line 8—8 of FIG. 6;

FIG. 9 is a cross-sectional view thereof taken through line 9—9 of FIG. 6; and,

FIG. 10 is a front perspective view of a heat radiation fin of heat insulating cylinder for manufacturing semiconductor wafers in use.

The broken lines are shown for illustrative purposes only and form no part of the claimed design.

**1 Claim, 3 Drawing Sheets**



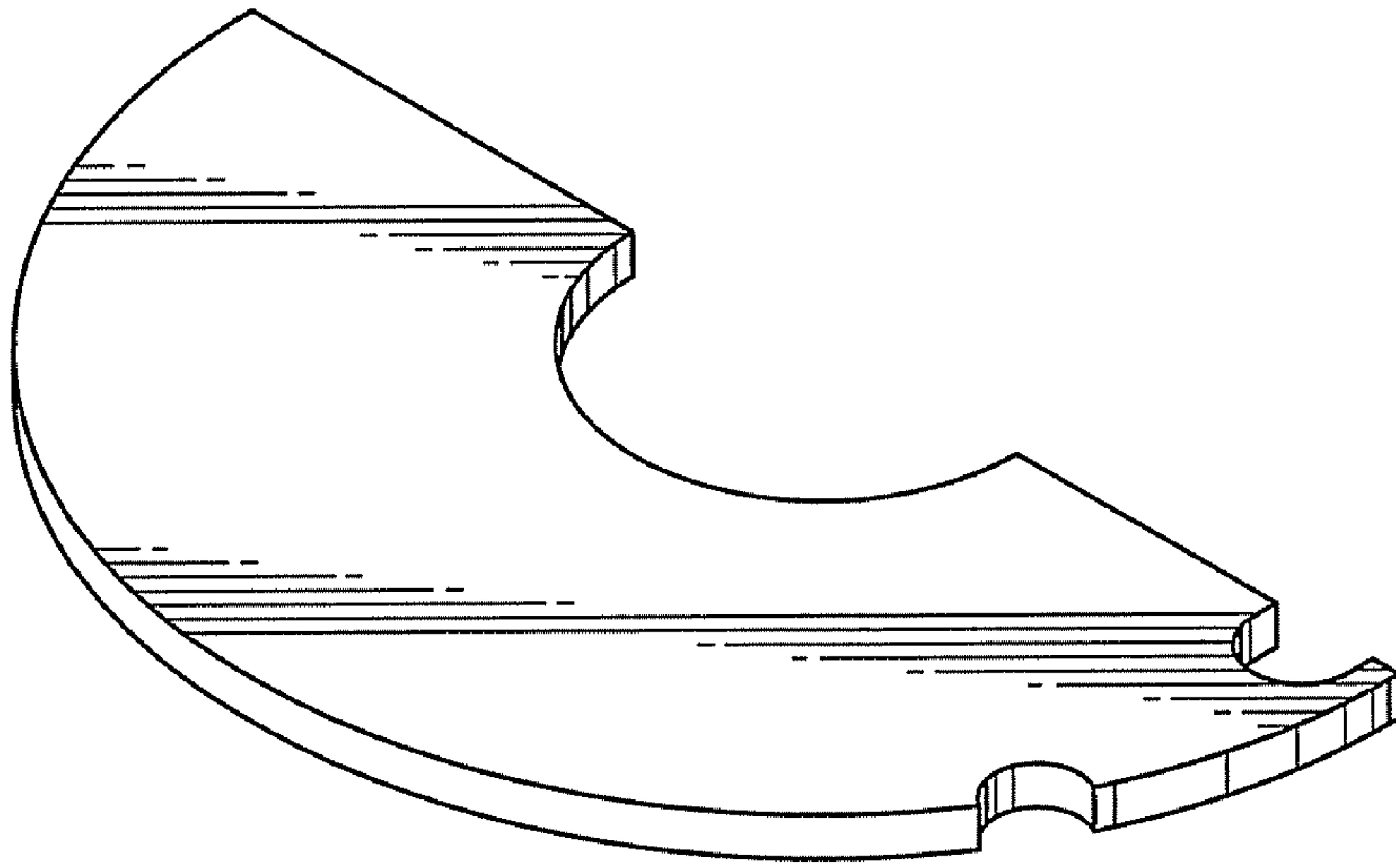


FIG. 1



FIG. 2



FIG. 3

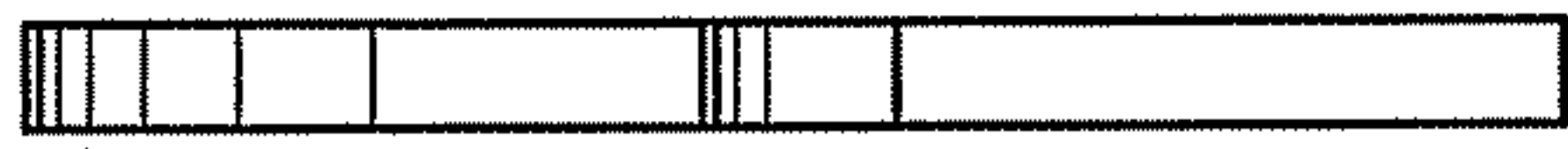


FIG. 4



FIG. 5

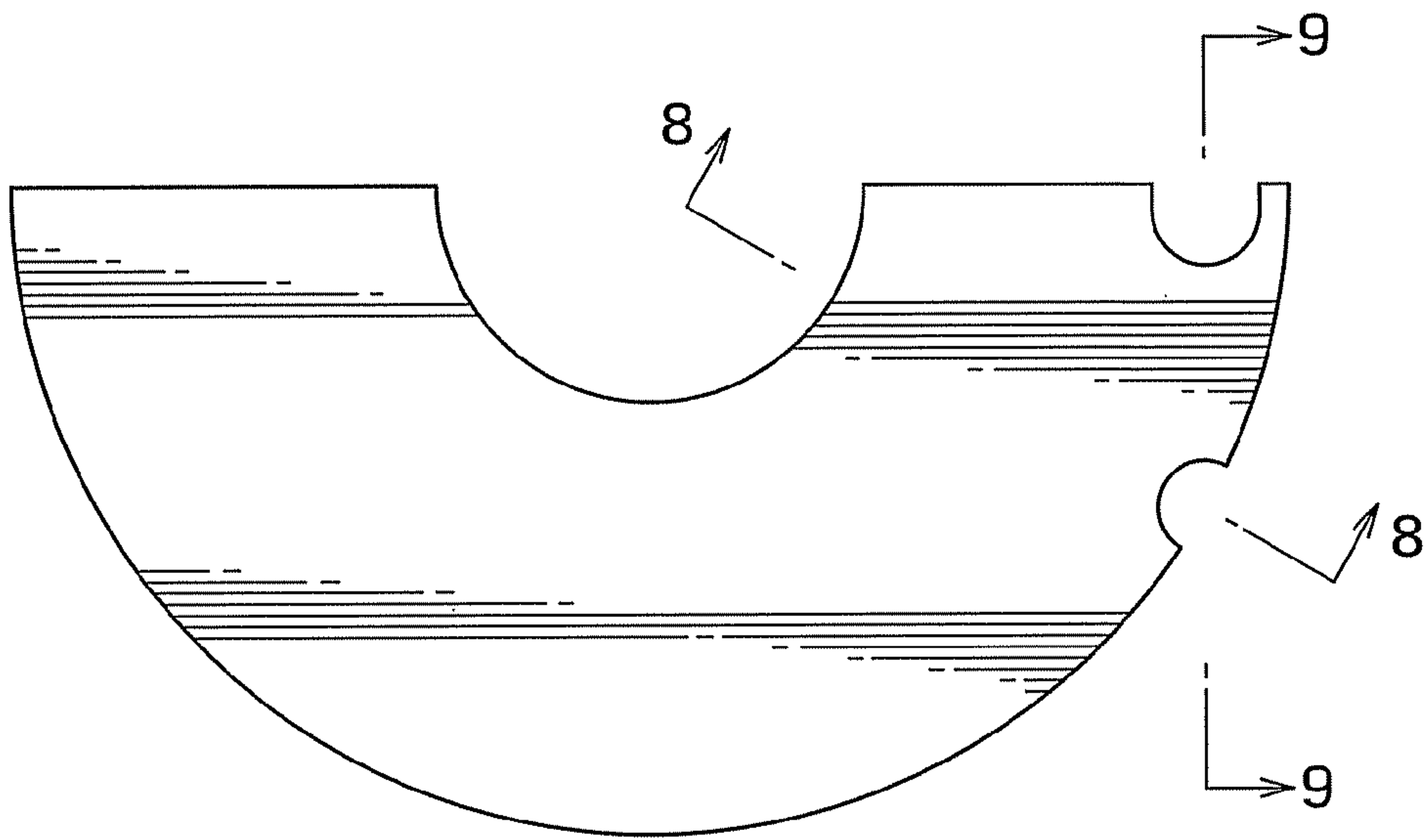


FIG. 6

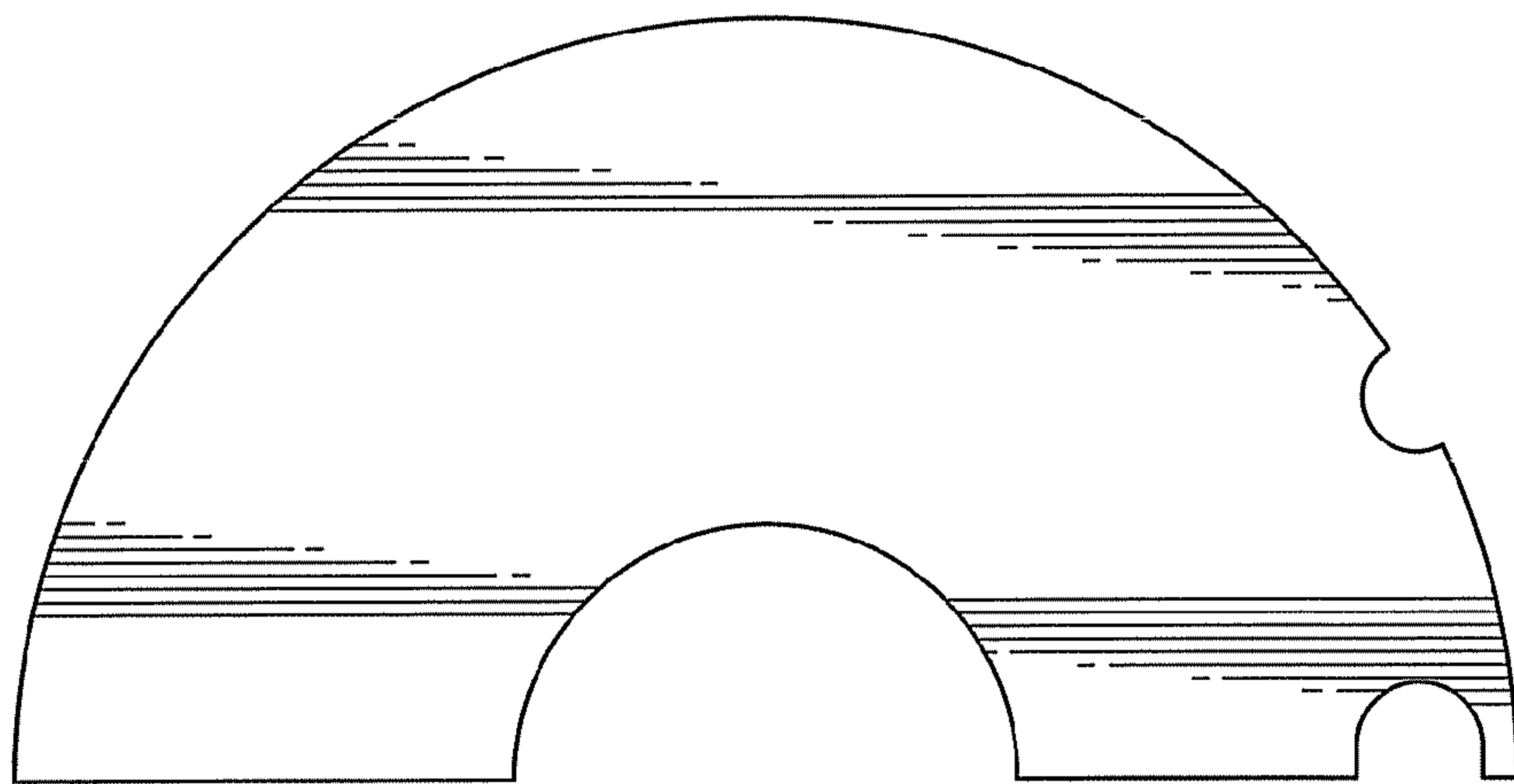


FIG. 7



FIG. 8



FIG. 9

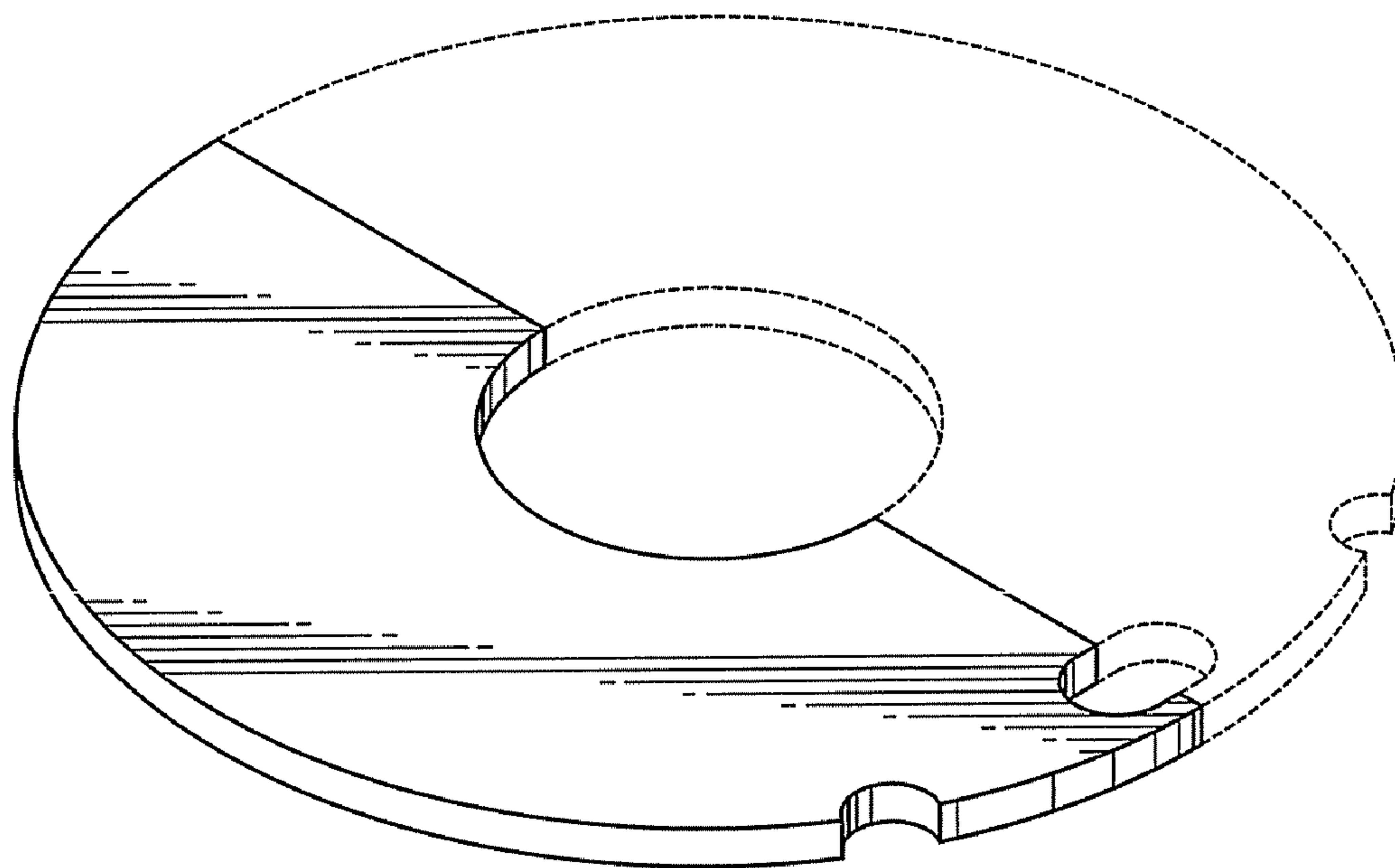


FIG. 10